In the Specification:

Please add a new section directly before "Technical Field" as follows:

CROSS-REFERENCE TO RELATED APPLICATION

This application is a divisional application of U.S. Patent Application No. 10/145,986, entitled "METHODS EMPLOYING ELEVATED TEMPERATURES TO ENHANCE QUALITY CONTROL IN MICROELECTRONIC COMPONENT MANUFACTURE," filed 15 May 2002, now U.S. Patent No. 6,720,195, issued 13 April 2004, which is herein incorporated by reference in its entirety.

Please amend paragraph [0008] as follows:

Figure 2 is a schematic flow diagram of the component packaging step of Figure ~~3~~ 1.

Please amend paragraphs [0010] and [0011] as follows:

Figure 4 is a schematic side view of a portion of the system of Figure 1 along line 4-4 in Figure ~~1~~ 3.

Figure 5 is a schematic cross-sectional view of a portion of the system of Figure 1, taken along line 5-5 Figure ~~1~~ 3.

Please amend paragraph [0019] as follows:

If so desired, these encapsulated subassemblies may be mounted on a mounting tape in step 26. In some embodiments, a series of individual subassemblies may be attached to a continuous mounting tape and the lead frame or other structure may be mounted on the same mounting tape adjacent. In other embodiments, a series of lead frames ~~my~~ may be attached to one another (e.g., as a strip or matrix of lead frame openings joined together by their respective dams) and each of the dies may be attached to a paddle or the like of a specific lead ~~from~~ by a separate small piece of mounting tape. Whether or not the encapsulated subassemblies are mounted on a mounting tape or the like in

step 26, a plurality of the encapsulated subassemblies is typically loaded into a magazine (step 28) for transport. Such magazines are well known in the art and available in a variety of custom or standard configurations.

Please amend paragraph [0030] as follows:

A pressurized air supply 160 may be used to circulate air within the oven chamber 150. In the illustrated embodiment, the air supply 160 comprises a blower 162 which delivers air to a plenum 164 which may extend along substantially the entire length of the heating apparatus 130. Pressurized air within the plenum 164 can be delivered to the oven chamber 150 through a series of passages 135 through the sidewall ~~143a~~134a. In one embodiment, a heat source may be included in the pressurized air supply 160 to deliver heated air to the oven chamber 150 to heat the microelectronic components. In such an embodiment, the control of the temperature profile along the length of the heating apparatus 130 may be substantially flat.

Please amend paragraph [0037] as follows:

The solder-bearing microelectronic components may be delivered from the solder plating apparatus 200 to a trim and form apparatus 220. The microelectronic components may be transported from the solder plating apparatus 200 to the trim and form apparatus 220 in any desired fashion. In the illustrated embodiment, the individual microelectronic components or strips of microelectronic components carried on mounting tape may be loaded into magazines in a second loading station 210. This second loading station may include two magazine bays 212a and ~~221b~~ 212b and a robot 214 to deliver the components or strips of components into the magazines. The magazines may then be transferred (schematically illustrated as paths 216) to the trim and form apparatus 220.